

TC74HC193AP, TC74HC193AF, TC74HC193AFN**SYNCHRONOUS UP/DOWN BINARY COUNTER**

The TC74HC193A are high speed CMOS SYNCHRONOUS 4-BIT UP/DOWN COUNTER fabricated with silicon gate C²MOS technology.

It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

They have a clear input (CLR), a load input (LOAD), load data inputs (A ~ D), two clock inputs (COUNT UP, COUNT DOWN), four count data outputs (QA ~ QD), and other outputs (CARRY, BORROW).

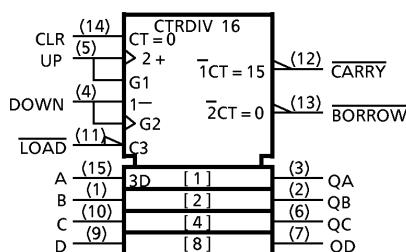
CLEAR is active high and forces QA thru QD outputs low independent of the other inputs.

CARRY and BORROW outputs are provided in order to make a cascade connection without external circuitry.

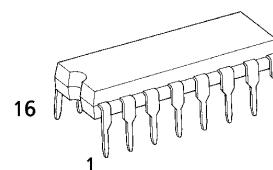
All inputs are equipped with protection circuits against static discharge or transient excess voltage.

FEATURES:

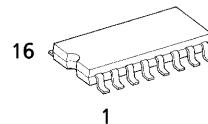
- High Speed.....f_{MAX} = 54MHz (typ.) at V_{CC} = 5V
- Low Power Dissipation.....I_{CC} = 4μA (Max.) at Ta = 25°C
- High Noise Immunity.....V_{NIH} = V_{NIL} = 28% V_{CC} (Min.)
- Output drive Capability.....10 LSTTL Loads
- Symmetrical Output Impedance.....| I_{OH} | = | I_{OL} | = 4mA (Min.)
- Balanced Propagation Delays.....t_{pLH} ≈ t_{pHL}
- Wide Operating Voltage Range.....V_{CC} (opr.) = 2V ~ 6V
- Pin and Function Compatible with 74LS193

IEC LOGIC SYMBOL

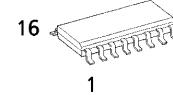
(Note) The JEDEC SOP (FN) is not available in Japan.



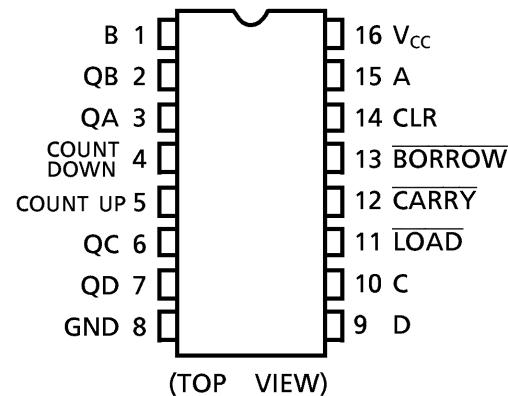
P (DIP16-P-300-2.54A)
Weight : 1.00g (Typ.)



F (SOP16-P-300-1.27)
Weight : 0.18g (Typ.)

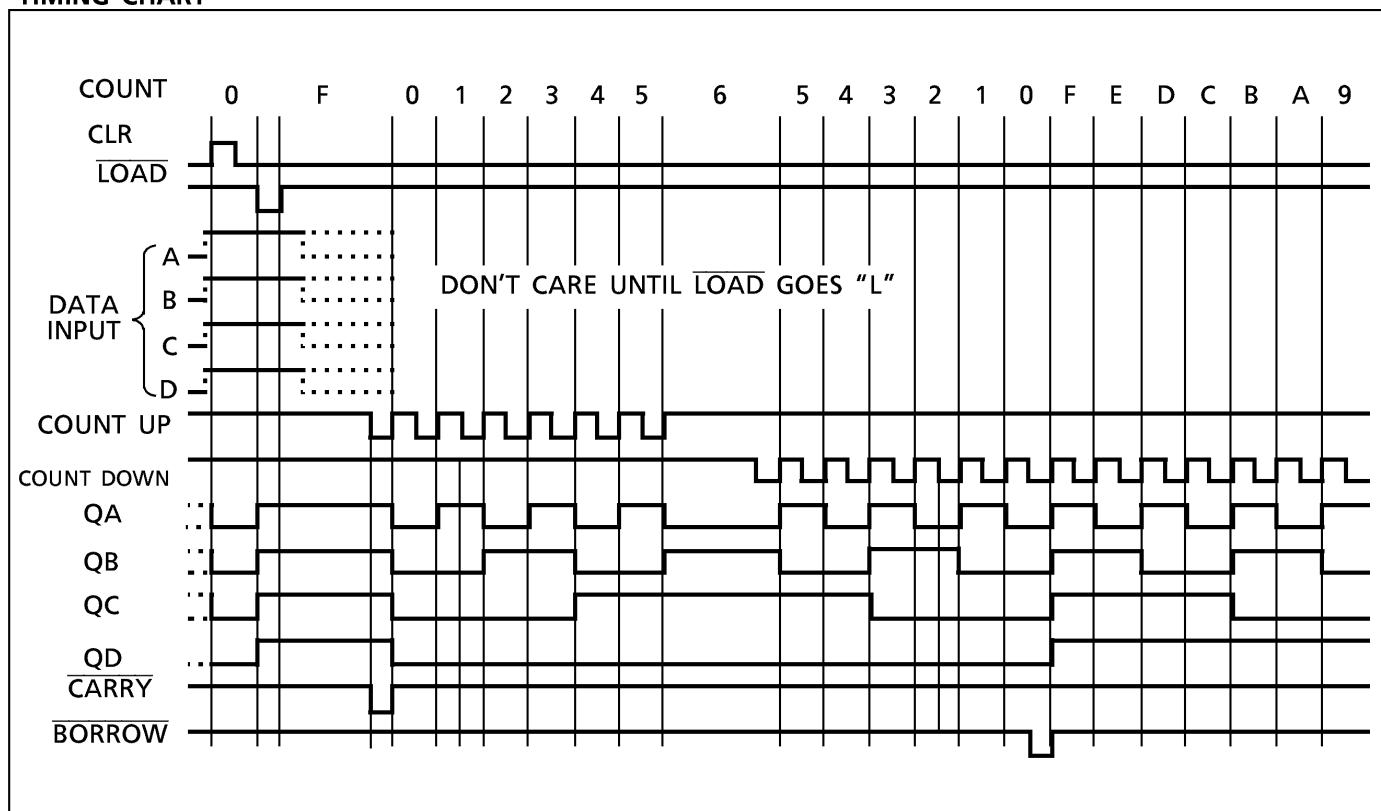


FN (SOL16-P-150-1.27)
Weight : 0.13g (Typ.)

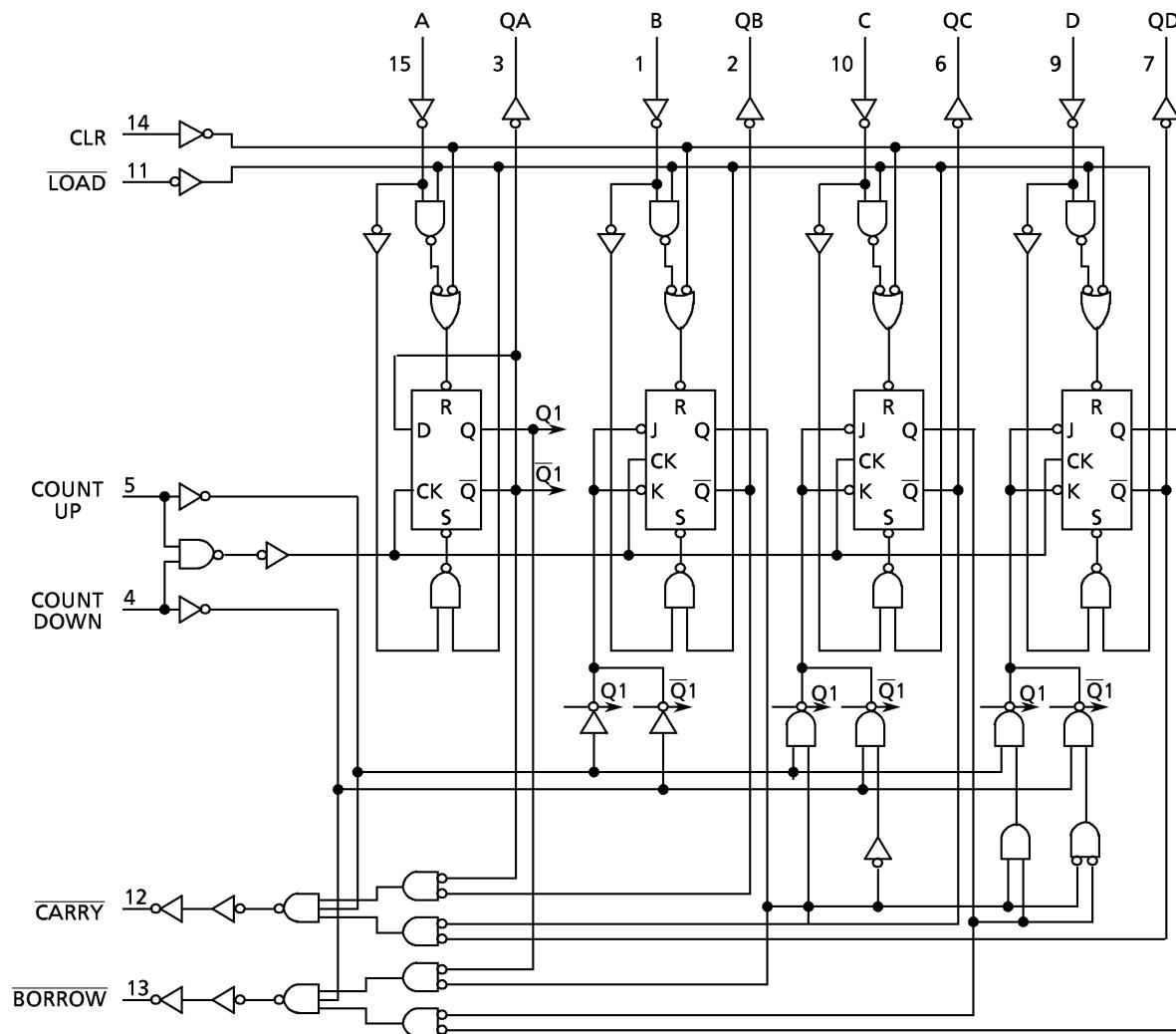
PIN ASSIGNMENT**TRUTH TABLE**

INPUTS				FUNCTION
COUNT UP	COUNT DOWN	LOAD	CLR	
↓	H	H	L	COUNT UP
↑	H	H	L	NO COUNT
H	↓	H	L	COUNT DOWN
H	↑	H	L	NO COUNT
X	X	L	L	PRESET
X	X	X	H	RESET

TIMING CHART



SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	-0.5~7	V
DC Input Voltage	V_{IN}	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 20	mA
DC Output Current	I_{OUT}	± 25	mA
DC V_{CC} / Ground Current	I_{CC}	± 50	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	T_{STG}	-65~150	°C

*500mW in the range of $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$. From $T_a = 65^{\circ}\text{C}$ to 85°C a derating factor of $-10\text{mW}/^{\circ}\text{C}$ shall be applied until 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	2~6	V
Input Voltage	V_{IN}	0~ V_{CC}	V
Output Voltage	V_{OUT}	0~ V_{CC}	V
Operating Temperature	T_{OPR}	-40~85	°C
Input Rise and Fall Time	t_r, t_f	0~1000 ($V_{CC} = 2.0\text{V}$) 0~500 ($V_{CC} = 4.5\text{V}$) 0~400 ($V_{CC} = 6.0\text{V}$)	ns

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V_{IH}		2.0	1.50	—	—	1.50	—	V
			4.5	3.15	—	—	3.15	—	
			6.0	4.20	—	—	4.20	—	
Low - Level Input Voltage	V_{IL}		2.0	—	—	0.50	—	0.50	V
			4.5	—	—	1.35	—	1.35	
			6.0	—	—	1.80	—	1.80	
High - Level Output Voltage	V_{OH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -20\mu\text{A}$	2.0	1.9	2.0	—	1.9	V
			$I_{OH} = -4\text{ mA}$	4.5	4.4	4.5	—	4.4	
			$I_{OH} = -5.2\text{ mA}$	6.0	5.9	6.0	—	5.9	
				4.5	4.18	4.31	—	4.13	
Low - Level Output Voltage	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 20\mu\text{A}$	6.0	5.68	5.80	—	5.63	V
			$I_{OL} = 4\text{ mA}$	2.0	—	0.0	0.1	—	
			$I_{OL} = 5.2\text{ mA}$	4.5	—	0.0	0.1	—	
				6.0	—	0.0	0.1	—	
Input Leakage Current	I_{IN}	$V_{IN} = V_{CC}$ or GND	6.0	—	—	± 0.1	—	± 1.0	μA
Quiescent Supply Current	I_{CC}	$V_{IN} = V_{CC}$ or GND	6.0	—	—	4.0	—	40.0	

TIMING REQUIREMENTS (Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	$V_{CC}(\text{V})$	$T_a = 25^\circ\text{C}$		$T_a = -40\text{--}85^\circ\text{C}$	UNIT
				TYP.	LIMIT	LIMIT	
Minimum Pulse Width (CK)	$t_{W(H)}$		2.0	—	100	125	ns
	$t_{W(L)}$		4.5	—	20	25	
			6.0	—	17	21	
Minimum Pulse Width (LOAD)	$t_{W(L)}$		2.0	—	75	95	ns
			4.5	—	15	19	
			6.0	—	13	16	
Minimum Hold Time (CLR)	$t_{W(H)}$		2.0	—	100	125	ns
			4.5	—	20	25	
			6.0	—	17	21	
Minimum Set-up Time (DATA—LOAD)	t_s		2.0	—	75	95	ns
			4.5	—	15	19	
			6.0	—	13	16	
Minimum Hold Time (DATA—LOAD)	t_h		2.0	—	0	0	ns
			4.5	—	0	0	
			6.0	—	0	0	
Minimum Removal Time (LOAD)	t_{rem}		2.0	—	50	65	ns
			4.5	—	10	13	
			6.0	—	9	10	
Minimum Removal Time (CLR)	t_{rem}		2.0	—	50	65	ns
			4.5	—	10	13	
			6.0	—	9	10	
Clock Frequency	f		2.0	—	5	4	MHz
			4.5	—	25	20	
			6.0	—	29	24	

AC ELECTRICAL CHARACTERISTICS ($C_L = 15\text{pF}$, $V_{CC} = 5\text{V}$, $T_a = 25^\circ\text{C}$, Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Transition Time	t_{TLH} t_{THL}		—	6	12	ns
Propagation Delay Time (UP, DOWN—Q)	t_{pLH} t_{pHL}		—	16	33	
Propagation Delay Time (UP—CARRY)	t_{pLH} t_{pHL}		—	10	22	
Propagation Delay Time (DOWN—BORROW)	t_{pLH} t_{pHL}		—	10	22	
Propagation Delay Time (LOAD—Q)	t_{pLH} t_{pHL}		—	21	38	
Propagation Delay Time (LOAD—CARRY)	t_{pLH} t_{pHL}		—	25	44	
Propagation Delay Time (LOAD—BORROW)	t_{pLH} t_{pHL}		—	26	44	
Propagation Delay Time (DATA IN—Q)	t_{pLH} t_{pHL}		—	21	33	
Propagation Delay Time (DATA IN—CARRY)	t_{pLH} t_{pHL}		—	29	44	
Propagation Delay Time (DATA IN—BORROW)	t_{pLH} t_{pHL}		—	26	44	
Propagation Delay Time (CLR—Q)	t_{pHL}		—	25	39	
Propagation Delay Time (CLR—CARRY)	t_{pLH}		—	30	44	
Propagation Delay Time (CLR—BORROW)	t_{pHL}		—	30	44	
Maximum Clock Frequency	f_{MAX}		27	52	—	MHz

AC ELECTRICAL CHARACTERISTICS ($C_L = 50\text{pF}$, Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	$V_{CC}(\text{V})$	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
Output Transition Time	t_{TLH}		2.0	—	30	75	—	95	ns
	t_{THL}		4.5	—	8	15	—	19	
Propagation Delay Time (UP, DOWN-Q)	t_{PLH}		6.0	—	7	13	—	16	
	t_{PHL}		2.0	—	65	190	—	240	
Propagation Delay Time (UP-CARRY)	t_{PLH}		4.5	—	20	38	—	48	
	t_{PHL}		6.0	—	16	32	—	41	
Propagation Delay Time (DOWN-BORROW)	t_{PLH}		2.0	—	40	130	—	165	
	t_{PHL}		4.5	—	13	26	—	33	
Propagation Delay Time (DOWN-BORROW)	t_{PLH}		6.0	—	11	22	—	28	
	t_{PHL}		2.0	—	40	130	—	165	
Propagation Delay Time (LOAD-Q)	t_{PLH}		4.5	—	13	26	—	33	
	t_{PHL}		6.0	—	11	22	—	28	
Propagation Delay Time (LOAD-CARRY)	t_{PLH}		2.0	—	85	220	—	275	
	t_{PHL}		4.5	—	25	44	—	55	
Propagation Delay Time (LOAD-BORROW)	t_{PLH}		6.0	—	20	37	—	47	
	t_{PHL}		2.0	—	110	250	—	315	
Propagation Delay Time (LOAD-BORROW)	t_{PLH}		4.5	—	30	50	—	63	
	t_{PHL}		6.0	—	25	43	—	54	
Propagation Delay Time (DATA IN-Q)	t_{PLH}		2.0	—	110	250	—	315	
	t_{PHL}		4.5	—	30	50	—	63	
Propagation Delay Time (DATA IN-Q)	t_{PLH}		6.0	—	25	43	—	54	
	t_{PHL}		2.0	—	80	190	—	240	
Propagation Delay Time (DATA IN-CARRY)	t_{PLH}		4.5	—	25	38	—	48	
	t_{PHL}		6.0	—	20	32	—	41	
Propagation Delay Time (DATA IN-CARRY)	t_{PLH}		2.0	—	120	250	—	315	
	t_{PHL}		4.5	—	34	50	—	63	
Propagation Delay Time (DATA IN-BORROW)	t_{PLH}		6.0	—	28	43	—	54	
	t_{PHL}		2.0	—	110	250	—	315	
Propagation Delay Time (DATA IN-BORROW)	t_{PLH}		4.5	—	31	50	—	63	
	t_{PHL}		6.0	—	25	43	—	54	
Propagation Delay Time (CLR-Q)	t_{PLH}		2.0	—	100	225	—	280	
	t_{PHL}		4.5	—	30	45	—	56	
Propagation Delay Time (CLR-Q)	t_{PLH}		6.0	—	25	38	—	48	
	t_{PHL}		2.0	—	120	250	—	315	
Propagation Delay Time (CLR-CARRY)	t_{PLH}		4.5	—	35	50	—	63	
	t_{PHL}		6.0	—	29	43	—	54	
Propagation Delay Time (CLR-BORROW)	t_{PLH}		2.0	—	120	250	—	315	
	t_{PHL}		4.5	—	35	50	—	63	
Propagation Delay Time (CLR-BORROW)	t_{PLH}		6.0	—	29	43	—	54	
	f_{MAX}		2.0	5	12	—	4	—	MHz
Input Capacitance	C_{IN}		4.5	25	48	—	20	—	
Power Dissipation Capacitance	$C_{PD}(1)$		6.0	29	55	—	24	—	
				—	5	10	—	10	pF
				—	67	—	—	—	

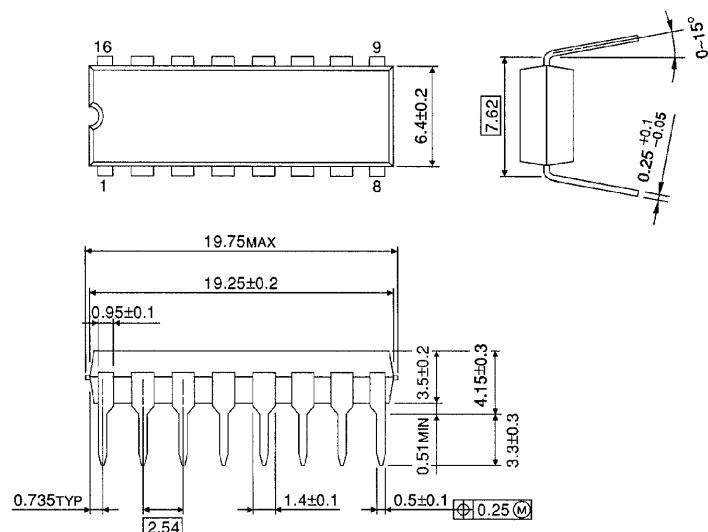
Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC}(\text{opr}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}$$

DIP 16PIN PACKAGE DIMENSIONS (DIP16-P-300-2.54A)

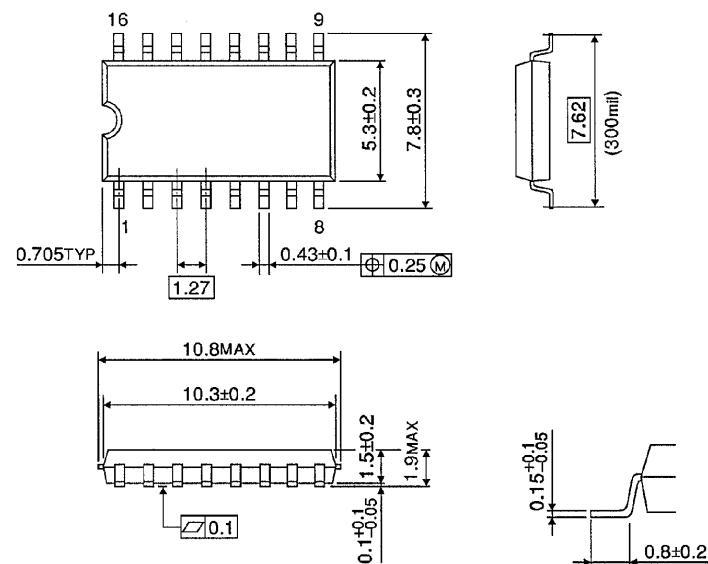
Unit in mm



Weight : 1.00g (Typ.)

SOP 16PIN (200mil BODY) PACKAGE DIMENSIONS (SOP16-P-300-1.27)

Unit in mm

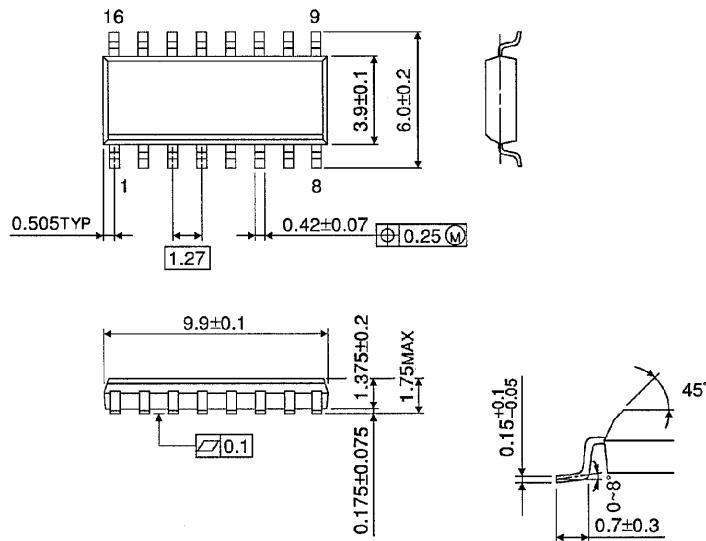


Weight : 0.18g (Typ.)

SOP 16PIN (150mil BODY) PACKAGE DIMENSIONS (SOL16-P-150 -1.27)

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.13g (Typ.)

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000707EBA

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